

LM4995 Boomer® Audio Power Amplifier Series 1.3 W Audio Power Amplifier

Check for Samples: [LM4995](#), [LM4995TMBD](#)

FEATURES

- Available in Space-Saving 0.4mm Pitch DSBGA Package
- Ultra Low Current Shutdown Mode
- BTL Output Can Drive Capacitive Loads
- Improved Click and Pop Circuitry Eliminates Noise during Turn-On and Turn-Off Transitions
- 2.4 - 5.5V Operation
- No Output Coupling Capacitors, Snubber Networks or Bootstrap Capacitors Required
- Unity-Gain Stable
- External Gain Configuration Capability
- WSON Package: 0.5mm Pitch, 3 x 3 mm

APPLICATIONS

- Mobile Phones
- PDAs
- Portable electronic devices

KEY SPECIFICATIONS

- PSRR at 3.6V (217Hz & 1kHz): 75 dB
- Output Power at 5.0V, 1% THD+N, 8Ω: 1.3 W (typ)
- Output Power at 3.6V, 1% THD+N, 8Ω: 625 mW (typ)
- Shutdown Current: 0.01μA (typ)

DESCRIPTION

The LM4995 is an audio power amplifier primarily designed for demanding applications in mobile phones and other portable communication device applications. It is capable of delivering 1.2W of continuous average power to an 8Ω BTL load with less than 1% distortion (THD+N) from a 5V_{DC} power supply.

Boomer audio power amplifiers were designed specifically to provide high quality output power with a minimal amount of external components. The LM4995 does not require output coupling capacitors or bootstrap capacitors, and therefore is ideally suited for mobile phone and other low voltage applications where minimal power consumption is a primary requirement.

The LM4995 features a low-power consumption shutdown mode, which is achieved by driving the shutdown pin with logic low. Additionally, the LM4995 features an internal thermal shutdown protection mechanism.

The LM4995 contains advanced click and pop circuitry which eliminates noise which would otherwise occur during turn-on and turn-off transitions.

The LM4995 is unity-gain stable and can be configured by external gain-setting resistors.



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TYPICAL APPLICATION

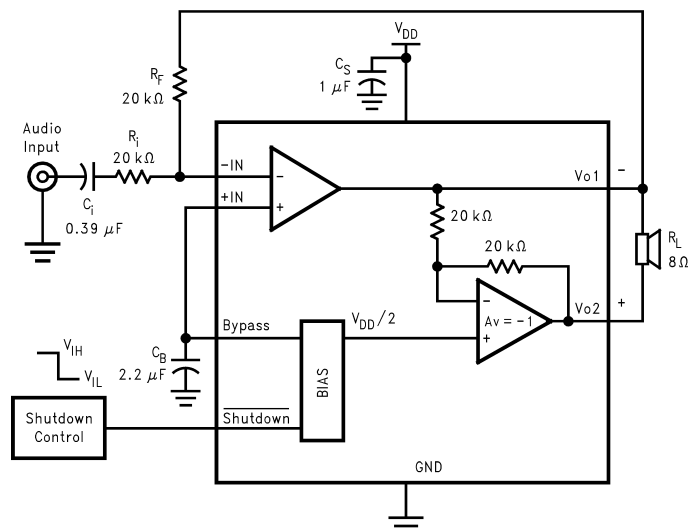


Figure 1. Typical Audio Amplifier Application Circuit

CONNECTION DIAGRAM

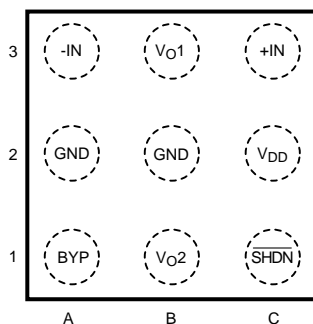


Figure 2. DSBGA (Top View)
See YFQ0009 Package

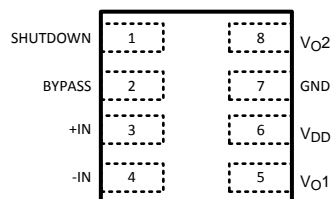


Figure 3. WSON (Top View)
See NGQ0008A Package



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾⁽²⁾

| | | |
|-------------------------------------|-----------------------|--------------------------------|
| Supply Voltage ⁽³⁾ | | 6.0V |
| Storage Temperature | | –65°C to +150°C |
| Input Voltage | | –0.3V to V _{DD} +0.3V |
| Power Dissipation ⁽⁴⁾⁽⁵⁾ | | Internally Limited |
| ESD Susceptibility ⁽⁶⁾ | | 2000V |
| ESD Susceptibility ⁽⁷⁾ | | 200V |
| Junction Temperature | | 150°C |
| Thermal Resistance | θ_{JA} (DSBGA) | 96.5°C/W |
| | θ_{JA} (WSON) | 56°C/W |

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensure for parameters where no limit is given, however, the typical value is a good indication of device performance.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (3) If the product is in Shutdown mode and V_{DD} exceeds 6V (to a max of 8V V_{DD}), then most of the excess current will flow through the ESD protection circuits. If the source impedance limits the current to a max of 10mA, then the device will be protected. If the device is enabled when V_{DD} is greater than 5.5V and less than 6.5V, no damage will occur, although operation life will be reduced. Operation above 6.5V with no current limit will result in permanent damage.
- (4) The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{JMAX}, θ_{JA} , and the ambient temperature T_A. The maximum allowable power dissipation is P_{DMAX} = (T_{JMAX}–T_A)/ θ_{JA} or the number given in Absolute Maximum Ratings, whichever is lower. For the LM4995, see power derating curves for additional information.
- (5) Maximum power dissipation in the device (P_{DMAX}) occurs at an output power level significantly below full output power. P_{DMAX} can be calculated using Equation 1 shown in the APPLICATION INFORMATION section. It may also be obtained from the power dissipation graphs.
- (6) Human body model, 100pF discharged through a 1.5k Ω resistor.
- (7) Machine Model, 220pF–240pF discharged through all pins.

OPERATING RATINGS

| | |
|---|-------------------------------|
| Temperature Range (T _{MIN} ≤ T _A ≤ T _{MAX}) | –40°C ≤ T _A ≤ 85°C |
| Supply Voltage | 2.4V ≤ V _{DD} ≤ 5.5V |

ELECTRICAL CHARACTERISTICS $V_{DD} = 5V^{(1)(2)}$

The following specifications apply for the circuit shown in [Figure 1](#), unless otherwise specified. Limits apply for $T_A = 25^\circ\text{C}$.

| Symbol | Parameter | Conditions | LM4995 | | Units (Limits) |
|------------|-----------------------------------|--|---------------------------------|-------------------------|-------------------|
| | | | Typical ⁽³⁾ | Limit ⁽⁴⁾⁽⁵⁾ | |
| I_{DD} | Quiescent Power Supply Current | $V_{IN} = 0V, I_o = 0A$, No Load | 1.5 | 2.5 | mA (max) |
| | | $V_{IN} = 0V, I_o = 0A$, 8 Ω Load | 1.8 | | mA |
| I_{SD} | Shutdown Current | $V_{SD} = V_{GND}$ | 0.01 | 1 | μA (max) |
| V_{OS} | Output Offset Voltage | No Load | 5 | 26 | mV (max) |
| P_o | Output Power | THD+N = 1% (max); f = 1 kHz | 1.3 (TM) 1.25 (SD) | | W |
| T_{WU} | Wake-up time | | 165 | | ms |
| THD+N | Total Harmonic Distortion + Noise | $P_o = 500mW_{RMS}$; f = 1kHz | 0.08 | | % |
| PSRR | Power Supply Rejection Ratio | $V_{ripple} = 200mV$ sine p-p Input terminated to GND | 73 (f = 217Hz) 73 (f = 1kHz) | | dB |
| V_{SDIH} | Shutdown Voltage Input High | | 1.5 | | V |
| V_{SDIL} | Shutdown Voltage Input Low | | 1.2 | | V |

(1) All voltages are measured with respect to the ground pin, unless otherwise specified.

(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensure for parameters where no limit is given, however, the typical value is a good indication of device performance.

(3) Typicals are measured at 25°C and represent the parametric norm.

(4) Limits are specified to AOQL (Average Outgoing Quality Level).

(5) Datasheet min/max specification limits are specified by design, test, or statistical analysis.

ELECTRICAL CHARACTERISTICS $V_{DD} = 3.6V^{(1)(2)}$

The following specifications apply for the circuit shown in [Figure 1](#), unless otherwise specified. Limits apply for $T_A = 25^\circ\text{C}$.

| Symbol | Parameter | Conditions | LM4995 | | Units (Limits) |
|------------|-----------------------------------|--|---------------------------------|-------------------------|-------------------|
| | | | Typical ⁽³⁾ | Limit ⁽⁴⁾⁽⁵⁾ | |
| I_{DD} | Quiescent Power Supply Current | $V_{IN} = 0V, I_o = 0A$, No Load | 1.3 | 2.3 | mA (max) |
| | | $V_{IN} = 0V, I_o = 0A$, 8 Ω Load | 1.6 | | mA |
| I_{SD} | Shutdown Current | $V_{SD} = V_{GND}$ | 0.01 | 1 | μA (max) |
| V_{OS} | Output Offset Voltage | No Load | 5 | 26 | mV (max) |
| P_o | Output Power | THD+N = 1% (max); f = 1 kHz | 625 (TM) 610 (SD) | | mW |
| T_{WU} | Wake-up time | | 130 | | ms |
| THD+N | Total Harmonic Distortion + Noise | $P_o = 300mW_{RMS}$; f = 1kHz | 0.07 | | % |
| PSRR | Power Supply Rejection Ratio | $V_{ripple} = 200mV$ sine p-p Input terminated to GND | 75 (f = 217Hz) 76 (f = 1kHz) | | dB |
| V_{SDIH} | Shutdown Voltage Input High | | 1.3 | | V |
| V_{SDIL} | Shutdown Voltage Input Low | | 1 | | V |

(1) All voltages are measured with respect to the ground pin, unless otherwise specified.

(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensure for parameters where no limit is given, however, the typical value is a good indication of device performance.

(3) Typicals are measured at 25°C and represent the parametric norm.

(4) Limits are specified to AOQL (Average Outgoing Quality Level).

(5) Datasheet min/max specification limits are specified by design, test, or statistical analysis.

ELECTRICAL CHARACTERISTICS $V_{DD} = 3.0V^{(1)(2)}$

The following specifications apply for the circuit shown in [Figure 1](#), unless otherwise specified. Limits apply for $T_A = 25^\circ C$.

| Symbol | Parameter | Conditions | LM4995 | | Units (Limits) |
|------------|-----------------------------------|--|---|-------------------------|-------------------|
| | | | Typical ⁽³⁾ | Limit ⁽⁴⁾⁽⁵⁾ | |
| I_{DD} | Quiescent Power Supply Current | $V_{IN} = 0V, I_o = 0A$, No Load | 1.3 | | mA |
| | | $V_{IN} = 0V, I_o = 0A$, 8Ω Load | 1.6 | | mA |
| I_{SD} | Shutdown Current | $V_{SD} = V_{GND}$ | 0.01 | | μA |
| V_{OS} | Output Offset Voltage | No Load | 5 | | mV |
| P_o | Output Power | THD+N = 1% (max); $f = 1$ kHz | 400 | | mW |
| T_{WU} | Wake-up time | | 110 | | ms |
| THD+N | Total Harmonic Distortion + Noise | $P_o = 250mW_{RMS}$; $f = 1$ kHz | 0.07 | | % |
| PSRR | Power Supply Rejection Ratio | $V_{ripple} = 200mV$ sine p-p Input terminated to GND | 74 ($f = 217Hz$) 75 ($f = 1kHz$) | | dB |
| V_{SDIH} | Shutdown Voltage Input High | | 1.2 | | V |
| V_{SDIL} | Shutdown Voltage Input Low | | 1 | | V |

- (1) All voltages are measured with respect to the ground pin, unless otherwise specified.
- (2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensure for parameters where no limit is given, however, the typical value is a good indication of device performance.
- (3) Typicals are measured at $25^\circ C$ and represent the parametric norm.
- (4) Limits are specified to AOQL (Average Outgoing Quality Level).
- (5) Datasheet min/max specification limits are specified by design, test, or statistical analysis.

EXTERNAL COMPONENTS DESCRIPTION

([Figure 1](#))

| Components | | Functional Description |
|------------|-------|---|
| 1. | R_i | Inverting input resistance which sets the closed-loop gain in conjunction with R_f . This resistor also forms a high pass filter with C_i at $f_C = 1/(2\pi R_i C_i)$. |
| 2. | C_i | Input coupling capacitor which blocks the DC voltage at the amplifiers input terminals. Also creates a highpass filter with R_i at $f_C = 1/(2\pi R_i C_i)$. Refer to the section, PROPER SELECTION OF EXTERNAL COMPONENTS , for an explanation of how to determine the value of C_i . |
| 3. | R_f | Feedback resistance which sets the closed-loop gain in conjunction with R_i . |
| 4. | C_S | Supply bypass capacitor which provides power supply filtering. Refer to the POWER SUPPLY BYPASSING section for information concerning proper placement and selection of the supply bypass capacitor. |
| 5. | C_B | Bypass pin capacitor which provides half-supply filtering. Refer to the section, PROPER SELECTION OF EXTERNAL COMPONENTS , for information concerning proper placement and selection of C_B . |

TYPICAL PERFORMANCE CHARACTERISTICS

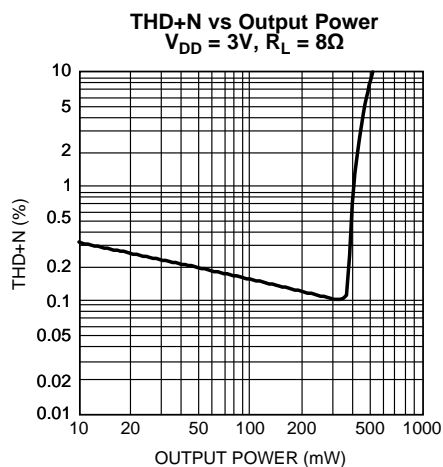


Figure 4.

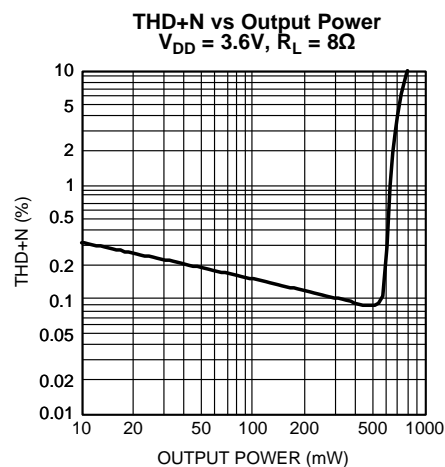


Figure 5.

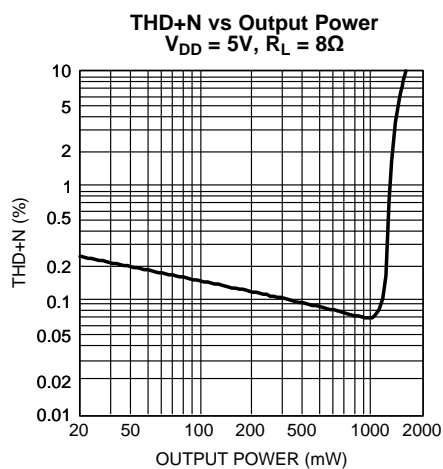


Figure 6.

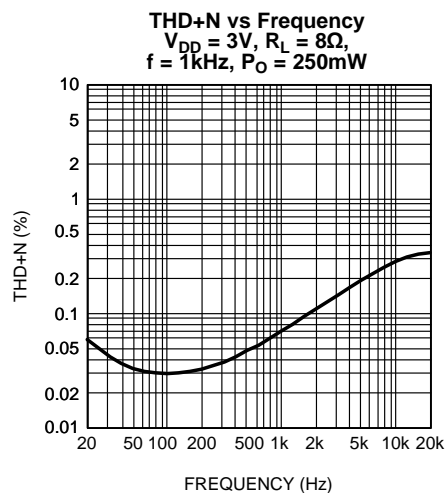


Figure 7.

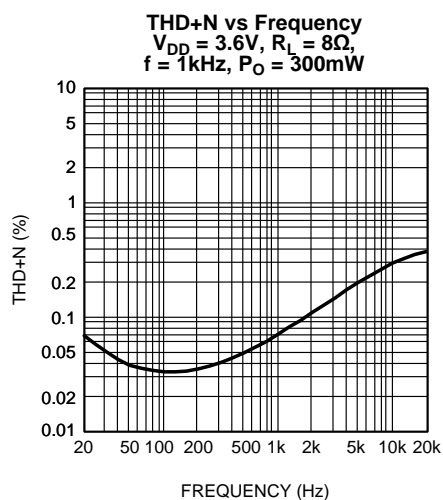


Figure 8.

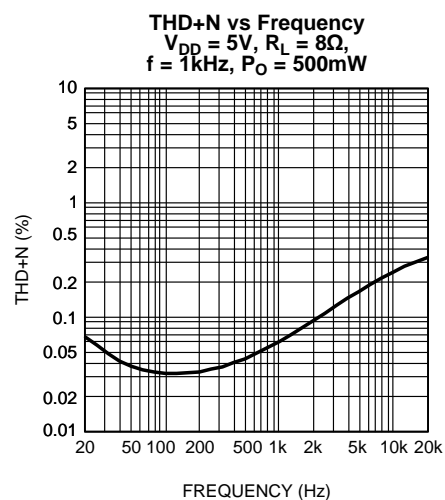


Figure 9.

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

PSRR vs Frequency
 $V_{DD} = 3V$, $R_L = 8\Omega$

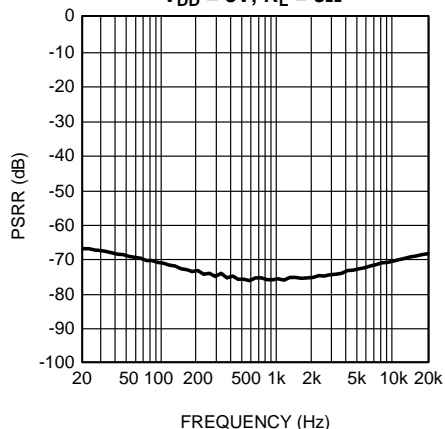


Figure 10.

PSRR vs Frequency
 $V_{DD} = 3.6V$, $R_L = 8\Omega$

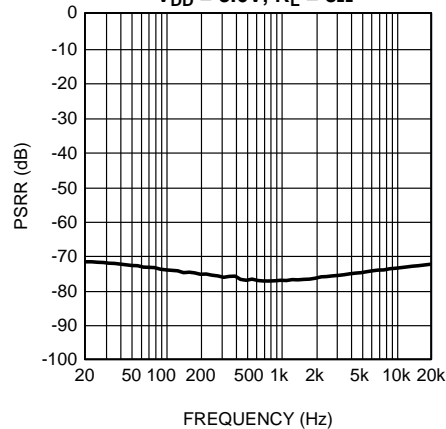


Figure 11.

PSRR vs Frequency
 $V_{DD} = 5V$, $R_L = 8\Omega$

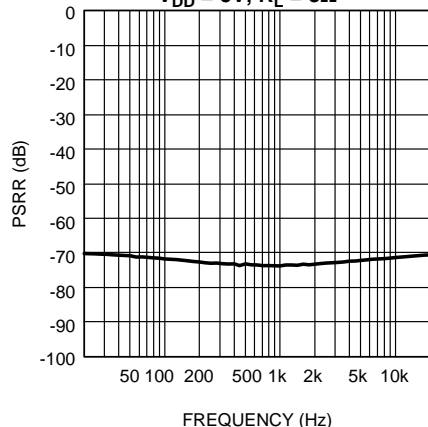


Figure 12.

Power Dissipation vs Output Power
 $V_{DD} = 3V$, $R_L = 8\Omega$

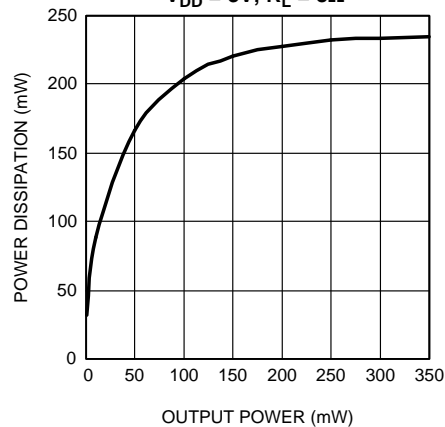


Figure 13.

Power Dissipation vs Output Power
 $V_{DD} = 3.6V$, $R_L = 8\Omega$

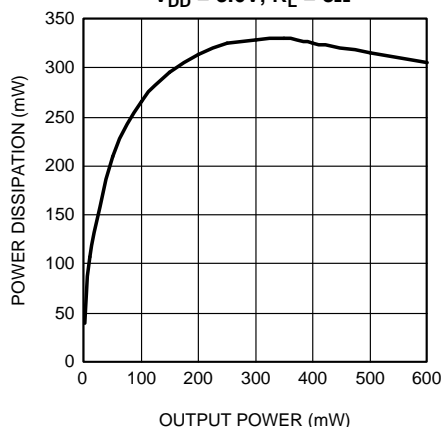


Figure 14.

Power Dissipation vs Output Power
 $V_{DD} = 5V$, $R_L = 8\Omega$

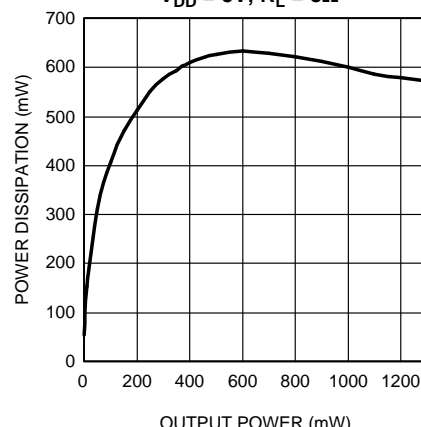
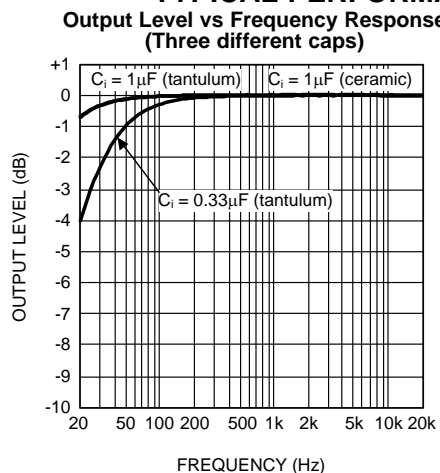
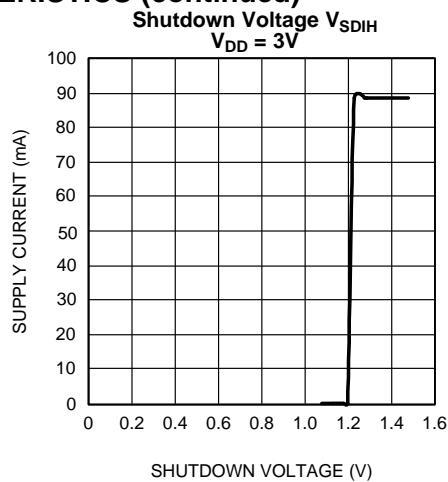
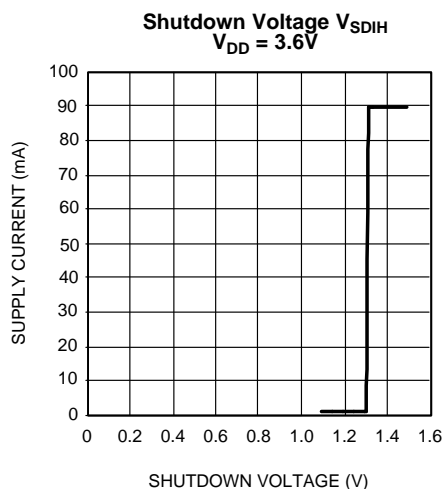
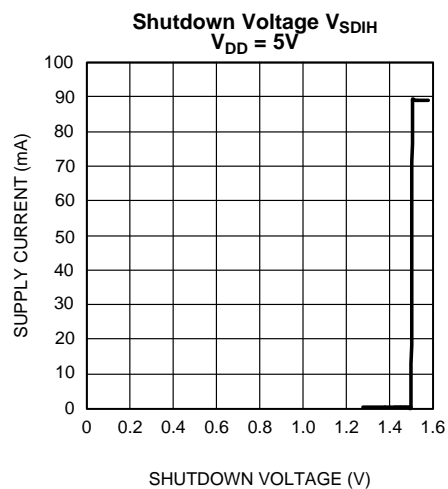
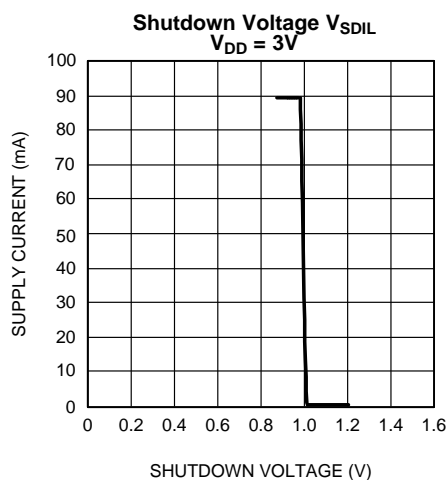
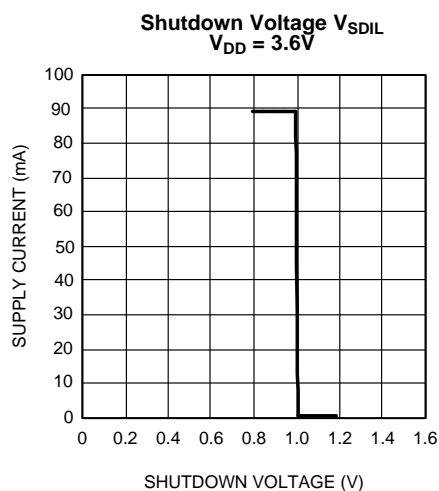
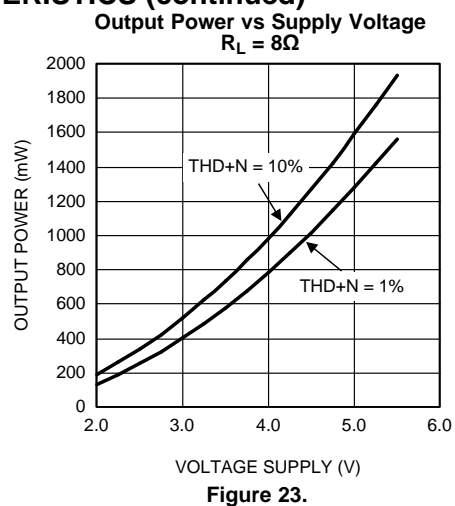
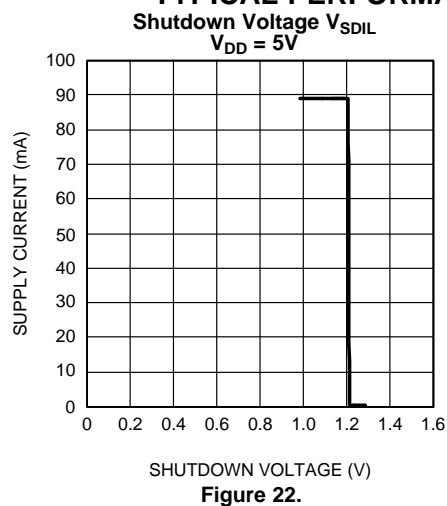


Figure 15.

TYPICAL PERFORMANCE CHARACTERISTICS (continued)**Figure 16.****Figure 17.****Figure 18.****Figure 19.****Figure 20.****Figure 21.**

TYPICAL PERFORMANCE CHARACTERISTICS (continued)



APPLICATION INFORMATION

BRIDGE CONFIGURATION EXPLANATION

As shown in [Figure 1](#), the LM4995 has two internal operational amplifiers. The first amplifier's gain is externally configurable, while the second amplifier is internally fixed in a unity-gain, inverting configuration. The closed-loop gain of the first amplifier is set by selecting the ratio of R_f to R_i while the second amplifier's gain is fixed by the two internal 20kΩ resistors. [Figure 1](#) shows that the output of amplifier one serves as the input to amplifier two which results in both amplifiers producing signals identical in magnitude, but out of phase by 180°. Consequently, the differential gain for the IC is

$$A_{VD} = 2 * (R_f/R_i) \quad (1)$$

By driving the load differentially through outputs Vo1 and Vo2, an amplifier configuration commonly referred to as “bridged mode” is established. Bridged mode operation is different from the classical single-ended amplifier configuration where one side of the load is connected to ground.

A bridge amplifier design has a few distinct advantages over the single-ended configuration, as it provides differential drive to the load, thus doubling output swing for a specified supply voltage. Four times the output power is possible as compared to a single-ended amplifier under the same conditions. This increase in attainable output power assumes that the amplifier is not current limited or clipped. In order to choose an amplifier's closed-loop gain without causing excessive clipping, please refer to the [AUDIO POWER AMPLIFIER DESIGN](#) section.

A bridge configuration, such as the one used in LM4995, also creates a second advantage over single-ended amplifiers. Since the differential outputs, Vo1 and Vo2, are biased at half-supply, no net DC voltage exists across the load. This eliminates the need for an output coupling capacitor which is required in a single supply, single-ended amplifier configuration. Without an output coupling capacitor, the half-supply bias across the load would result in both increased internal IC power dissipation and also possible loudspeaker damage.

POWER DISSIPATION

Power dissipation is a major concern when designing a successful amplifier, whether the amplifier is bridged or single-ended. A direct consequence of the increased power delivered to the load by a bridge amplifier is an increase in internal power dissipation. Since the LM4995 has two operational amplifiers in one package, the maximum internal power dissipation is 4 times that of a single-ended amplifier. The maximum power dissipation for a given application can be derived from the power dissipation graphs or from [Equation \(1\)](#).

$$P_{DMAX} = 4 * (V_{DD})^2 / (2\pi^2 R_L) \quad (2)$$

It is critical that the maximum junction temperature T_{JMAX} of 150°C is not exceeded. T_{JMAX} can be determined from the power derating curves by using P_{DMAX} and the PC board foil area. By adding copper foil, the thermal resistance of the application can be reduced from the free air value of θ_{JA} , resulting in higher P_{DMAX} values without thermal shutdown protection circuitry being activated. Additional copper foil can be added to any of the leads connected to the LM4995. It is especially effective when connected to V_{DD} , GND, and the output pins. Refer to the application information on the LM4995 reference design board for an example of good heat sinking. If T_{JMAX} still exceeds 150°C, then additional changes must be made. These changes can include reduced supply voltage, higher load impedance, or reduced ambient temperature. Internal power dissipation is a function of output power. Refer to the [TYPICAL PERFORMANCE CHARACTERISTICS](#) curves for power dissipation information for different output powers and output loading.

POWER SUPPLY BYPASSING

As with any amplifier, proper supply bypassing is critical for low noise performance and high supply rejection. The capacitor location on both the bypass and power supply pins should be as close to the device as possible. A ceramic 0.1μF placed in parallel with the tantalum 2.2μF bypass (C_B) capacitor will aid in supply stability. This does not eliminate the need for bypassing the power supply pins of the LM4995. The selection of a bypass capacitor, especially C_B , is dependent upon PSRR requirements, click and pop performance (as explained in the section, [PROPER SELECTION OF EXTERNAL COMPONENTS](#)), system cost, and size constraints.

SHUTDOWN FUNCTION

In order to reduce power consumption while not in use, the LM4995 contains shutdown circuitry that is used to turn off the amplifier's bias circuitry. This shutdown feature turns the amplifier off when logic low is placed on the shutdown pin. By switching the shutdown pin to GND, the LM4995 supply current draw will be minimized in idle mode. Idle current is measured with the shutdown pin connected to GND. The trigger point for shutdown is shown as a typical value in the Shutdown Hysteresis Voltage graphs in the [TYPICAL PERFORMANCE CHARACTERISTICS](#) section. It is best to switch between ground and supply for maximum performance. While the device may be disabled with shutdown voltages in between ground and supply, the idle current may be greater than the typical value of 0.01μA. In either case, the shutdown pin should be tied to a definite voltage to avoid unwanted state changes.

In many applications, a microcontroller or microprocessor output is used to control the shutdown circuitry, which provides a quick, smooth transition to shutdown. Another solution is to use a single-throw switch in conjunction with an external pull-up resistor. This scheme ensures that the shutdown pin will not float, thus preventing unwanted state changes.

PROPER SELECTION OF EXTERNAL COMPONENTS

Proper selection of external components in applications using integrated power amplifiers is critical to optimize device and system performance. While the LM4995 is tolerant of external component combinations, consideration to component values must be used to maximize overall system quality.

The LM4995 is unity-gain stable which gives the designer maximum system flexibility. The LM4995 should be used in low gain configurations to minimize THD+N values, and maximize the signal to noise ratio. Low gain configurations require large input signals to obtain a given output power. Input signals equal to or greater than 1 V_{rms} are available from sources such as audio codecs. Please refer to the section, [AUDIO POWER AMPLIFIER DESIGN](#), for a more complete explanation of proper gain selection.

Besides gain, one of the major considerations is the closed-loop bandwidth of the amplifier. To a large extent, the bandwidth is dictated by the choice of external components shown in [Figure 1](#). The input coupling capacitor, C_i, forms a first order high pass filter which limits low frequency response. This value should be chosen based on needed frequency response for a few distinct reasons.

SELECTION OF INPUT CAPACITOR SIZE

Large input capacitors are both expensive and space hungry for portable designs. Clearly, a certain sized capacitor is needed to couple in low frequencies without severe attenuation. But in many cases the speakers used in portable systems, whether internal or external, have little ability to reproduce signals below 100Hz to 150Hz. Thus, using a large input capacitor may not increase actual system performance.

In addition to system cost and size, click and pop performance is effected by the size of the input coupling capacitor, C_i. A larger input coupling capacitor requires more charge to reach its quiescent DC voltage (nominally 1/2 V_{DD}). This charge comes from the output via the feedback and is apt to create pops upon device enable. Thus, by minimizing the capacitor size based on necessary low frequency response, turn-on pops can be minimized.

Besides minimizing the input capacitor size, careful consideration should be paid to the bypass capacitor value. Bypass capacitor, C_B, is the most critical component to minimize turn-on pops since it determines how fast the LM4995 turns on. The slower the LM4995's outputs ramp to their quiescent DC voltage (nominally 1/2 V_{DD}), the smaller the turn-on pop. Choosing C_B equal to 1.0μF along with a small value of C_i (in the range of 0.1μF to 0.39μF), should produce a virtually clickless and popless shutdown function. While the device will function properly, (no oscillations or motorboating), with C_B equal to 0.1μF, the device will be much more susceptible to turn-on clicks and pops. Thus, a value of C_B equal to 1.0μF is recommended in all but the most cost sensitive designs.

AUDIO POWER AMPLIFIER DESIGN

A 1W/8Ω AUDIO AMPLIFIER

| | |
|-----------------|-------------------------|
| Given: | |
| Power Output | 1 Wrms |
| Load Impedance | 8Ω |
| Input Level | 1 Vrms |
| Input Impedance | 20 kΩ |
| Bandwidth | 100 Hz–20 kHz ± 0.25 dB |

A designer must first determine the minimum supply rail to obtain the specified output power. By extrapolating from the Output Power vs Supply Voltage graphs in the [TYPICAL PERFORMANCE CHARACTERISTICS](#) section, the supply rail can be easily found.

5V is a standard voltage in most applications, it is chosen for the supply rail. Extra supply voltage creates headroom that allows the LM4995 to reproduce peaks in excess of 1W without producing audible distortion. At this time, the designer must make sure that the power supply choice along with the output impedance does not violate the conditions explained in the [POWER DISSIPATION](#) section.

Once the power dissipation equations have been addressed, the required differential gain can be determined from [Equation \(3\)](#).

$$A_{VD} \geq \sqrt{(P_O R_L)} / (V_{IN}) = V_{orms} / V_{inrms} \quad (3)$$

$$R_f / R_i = A_{VD} / 2 \quad (4)$$

From [Equation \(3\)](#), the minimum A_{VD} is 2.83; use $A_{VD} = 3$.

Since the desired input impedance was 20 kΩ, and with a A_{VD} impedance of 2, a ratio of 1.5:1 of R_f to R_i results in an allocation of $R_i = 20$ kΩ and $R_f = 30$ kΩ. The final design step is to address the bandwidth requirements which must be stated as a pair of –3 dB frequency points. Five times away from a –3 dB point is 0.17 dB down from passband response which is better than the required ±0.25 dB specified.

$$f_L = 100\text{Hz} / 5 = 20\text{Hz}$$

$$f_H = 20\text{kHz} * 5 = 100\text{kHz}$$

As stated in the [EXTERNAL COMPONENTS DESCRIPTION](#) section, R_i in conjunction with C_i create a highpass filter.

$$C_i \geq 1 / (2\pi * 20 \text{ k}\Omega * 20 \text{ Hz}) = 0.397 \text{ }\mu\text{F}; \text{ use } 0.39 \text{ }\mu\text{F}$$

The high frequency pole is determined by the product of the desired frequency pole, f_H , and the differential gain, A_{VD} . With a $A_{VD} = 3$ and $f_H = 100\text{kHz}$, the resulting GBWP = 300kHz which is much smaller than the LM4995 GBWP of 2.5MHz. This figure displays that if a designer has a need to design an amplifier with a higher differential gain, the LM4995 can still be used without running into bandwidth limitations.

The LM4995 is unity-gain stable and requires no external components besides gain-setting resistors, an input coupling capacitor, and proper supply bypassing in the typical application. However, if a closed-loop differential gain of greater than 10 is required, a feedback capacitor (C_4) may be needed as shown in [Figure 24](#) to bandwidth limit the amplifier. This feedback capacitor creates a low pass filter that eliminates possible high frequency oscillations. Care should be taken when calculating the –3dB frequency in that an incorrect combination of R_3 and C_4 will cause rolloff before 20kHz. A typical combination of feedback resistor and capacitor that will not produce audio band high frequency rolloff is $R_3 = 20\text{k}\Omega$ and $C_4 = 25\text{pf}$. These components result in a –3dB point of approximately 320kHz.

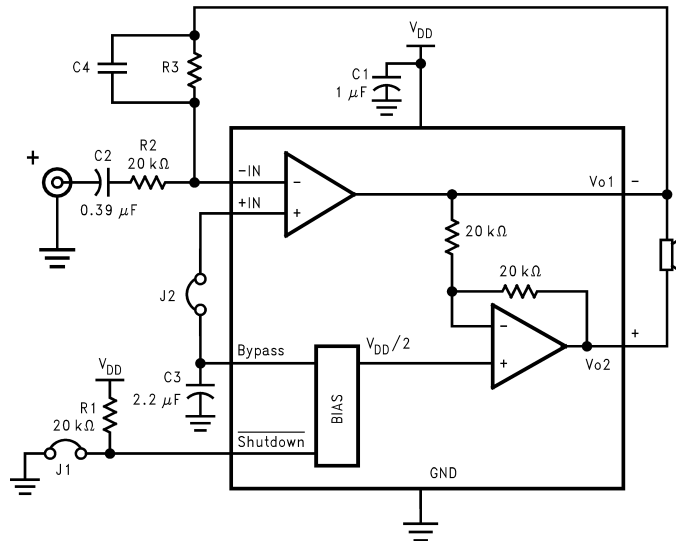


Figure 24. HIGHER GAIN AUDIO AMPLIFIER

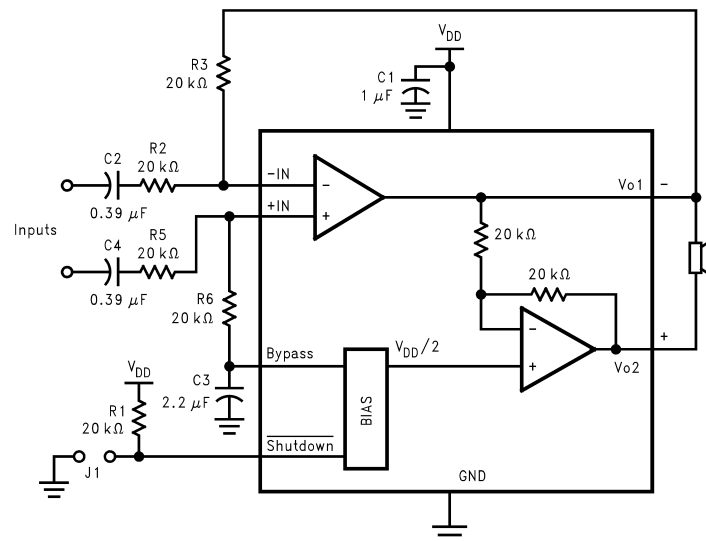
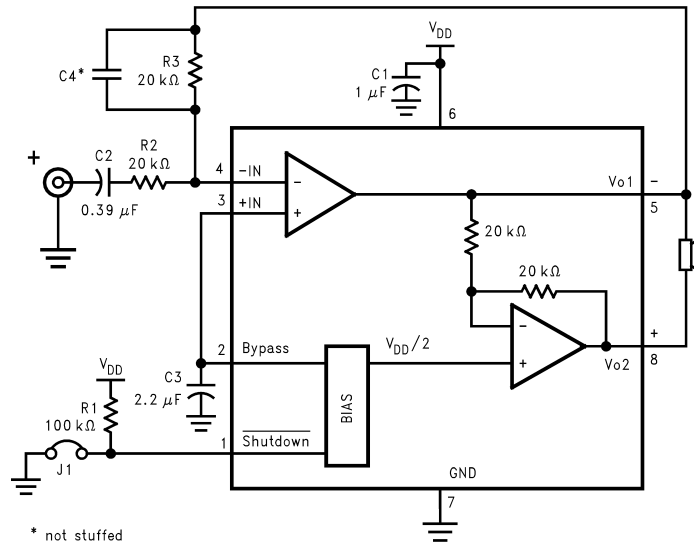


Figure 25. DIFFERENTIAL AMPLIFIER CONFIGURATION FOR LM4995

**Figure 26. REFERENCE DESIGN BOARD SCHEMATIC**

PCB LAYOUT GUIDELINES

This section provides practical guidelines for mixed signal PCB layout that involves various digital/analog power and ground traces. Designers should note that these are only "rule-of-thumb" recommendations and the actual results will depend heavily on the final layout.

GENERAL MIXED SIGNAL LAYOUT RECOMMENDATION

POWER AND GROUND CIRCUITS

For 2 layer mixed signal design, it is important to isolate the digital power and ground trace paths from the analog power and ground trace paths. Star trace routing techniques (bringing individual traces back to a central point rather than daisy chaining traces together in a serial manner) can have a major impact on low level signal performance. Star trace routing refers to using individual traces to feed power and ground to each circuit or even device. This technique will require a greater amount of design time but will not increase the final price of the board. The only extra parts required will be some jumpers.

SINGLE-POINT POWER / GROUND CONNECTIONS

The analog power traces should be connected to the digital traces through a single point (link). A "Pi-filter" can be helpful in minimizing High Frequency noise coupling between the analog and digital sections. It is further recommended to put digital and analog power traces over the corresponding digital and analog ground traces to minimize noise coupling.

PLACEMENT OF DIGITAL AND ANALOG COMPONENTS

All digital components and high-speed digital signal traces should be located as far away as possible from analog components and circuit traces.

AVOIDING TYPICAL DESIGN / LAYOUT PROBLEMS

Avoid ground loops or running digital and analog traces parallel to each other (side-by-side) on the same PCB layer. When traces must cross over each other do it at 90 degrees. Running digital and analog traces at 90 degrees to each other from the top to the bottom side as much as possible will minimize capacitive noise coupling and cross talk.

REVISION HISTORY

| Rev | Date | Description |
|-----|----------|---|
| 1.0 | 04/05/06 | Initial WEB released of the datasheet. |
| 1.1 | 05/17/06 | Added the SD package. |
| 1.2 | 08/07/06 | Text edits. |
| 1.3 | 08/22/06 | Edited the THD+N Typical values on the 3 EC tables, then re-released the D/S to the WEB (per Allan S.). |
| 1.4 | 09/11/07 | Updated the SD pkg. diagram. |

Changes from Revision F (April 2013) to Revision G

Page

- Changed layout of National Data Sheet to TI format [14](#)

PACKAGING INFORMATION

| Orderable part number | Status (1) | Material type (2) | Package Pins | Package qty Carrier | RoHS (3) | Lead finish/ Ball material (4) | MSL rating/ Peak reflow (5) | Op temp (°C) | Part marking (6) |
|--------------------------------|---------------|----------------------|-----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| LM4995SD/NOPB | Active | Production | WSON (NGQ) 8 | 1000 LARGE T&R | Yes | SN | Level-1-260C-UNLIM | - | L4995 |
| LM4995SD/NOPB.A | Active | Production | WSON (NGQ) 8 | 1000 LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 85 | L4995 |
| LM4995TM/NOPB | Active | Production | DSBGA (YFQ) 9 | 250 SMALL T&R | Yes | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | G G8 |
| LM4995TM/NOPB.A | Active | Production | DSBGA (YFQ) 9 | 250 SMALL T&R | Yes | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | G G8 |
| LM4995TMX/NOPB | Active | Production | DSBGA (YFQ) 9 | 3000 LARGE T&R | Yes | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | G G8 |
| LM4995TMX/NOPB.A | Active | Production | DSBGA (YFQ) 9 | 3000 LARGE T&R | Yes | SNAGCU | Level-1-260C-UNLIM | -40 to 85 | G G8 |

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| LM4995SD/NOPB | WSO | NGQ | 8 | 1000 | 177.8 | 12.4 | 3.3 | 3.3 | 1.0 | 8.0 | 12.0 | Q1 |
| LM4995TM/NOPB | DSBGA | YFQ | 9 | 250 | 178.0 | 8.4 | 1.35 | 1.35 | 0.76 | 4.0 | 8.0 | Q1 |
| LM4995TMX/NOPB | DSBGA | YFQ | 9 | 3000 | 178.0 | 8.4 | 1.35 | 1.35 | 0.76 | 4.0 | 8.0 | Q1 |

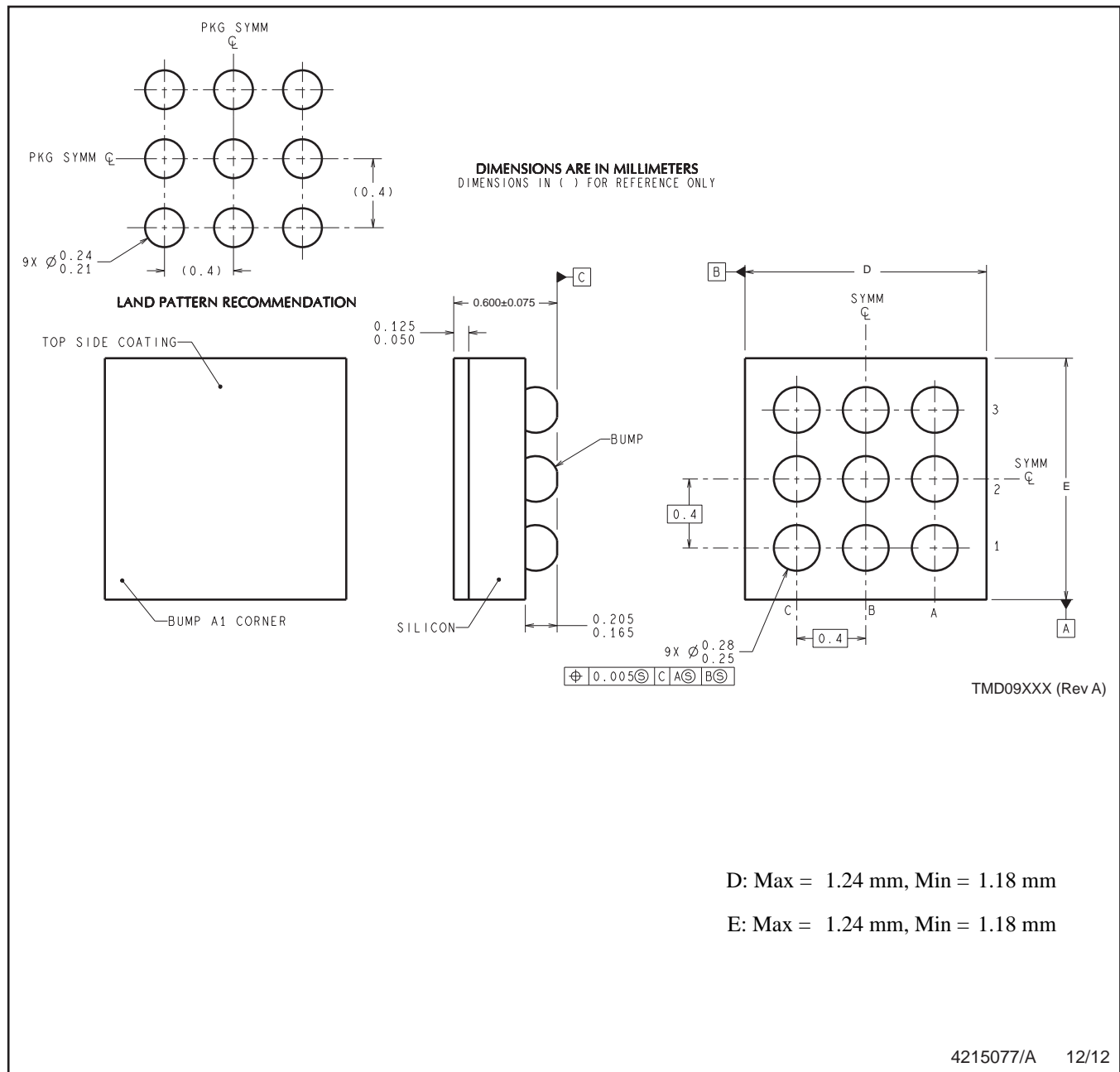
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LM4995SD/NOPB | WSON | NGQ | 8 | 1000 | 208.0 | 191.0 | 35.0 |
| LM4995TM/NOPB | DSBGA | YFQ | 9 | 250 | 208.0 | 191.0 | 35.0 |
| LM4995TMX/NOPB | DSBGA | YFQ | 9 | 3000 | 208.0 | 191.0 | 35.0 |

YFQ0009



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.

4215077/A 12/12



WSON - 0.8 mm max height

Technical drawing of a microelectronic package showing three views: a top view, a side view, and a bottom view.

Top View: Shows a square package. The width is 3.1, and the distance from the right edge to the center of the PIN 1 INDEX AREA is 2.9. The PIN 1 INDEX AREA is indicated by a hatched pattern.

Side View: Shows the package height. The total height is 0.8, and the seating plane is at 0.7 from the bottom.

Bottom View: Shows the package footprint. The width is 1.6 ± 0.1. The package is symmetrical (SYMM) about a vertical centerline. The pin pitch is 1.5 (2X) and 0.5 (6X). The pin width is 0.3 (8X). The package is seated on a seating plane. The bottom view also shows a central pin (9) and side pins (4 and 5). The distance from the bottom edge to the center of the package is 2 ± 0.1. The distance from the bottom edge to the center of the package is 8X 0.3. The distance from the bottom edge to the center of the package is 8X 0.5. The distance from the bottom edge to the center of the package is 8X 0.3.

Table:

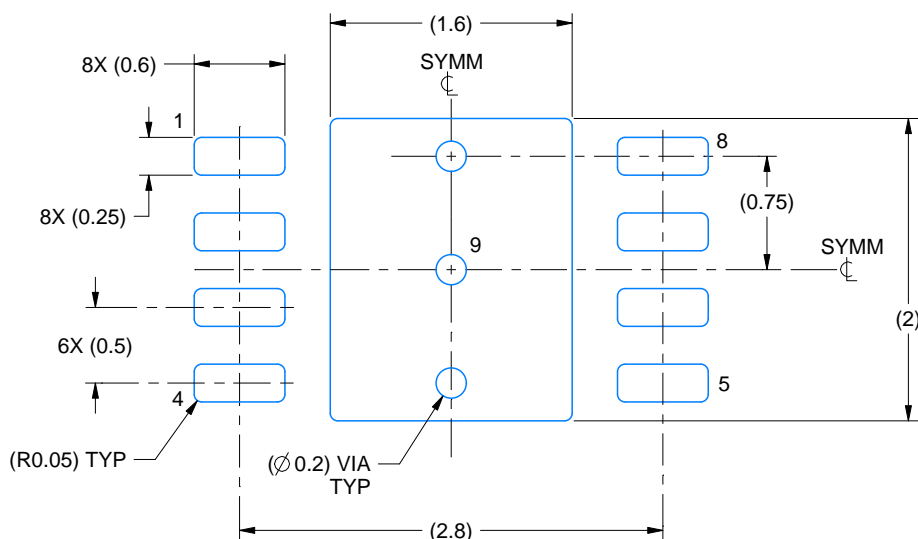
| | | | | | |
|---|------|---|---|---|---|
| ⊕ | 0.1 | Ⓜ | C | A | B |
| | 0.05 | Ⓜ | C | | |

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

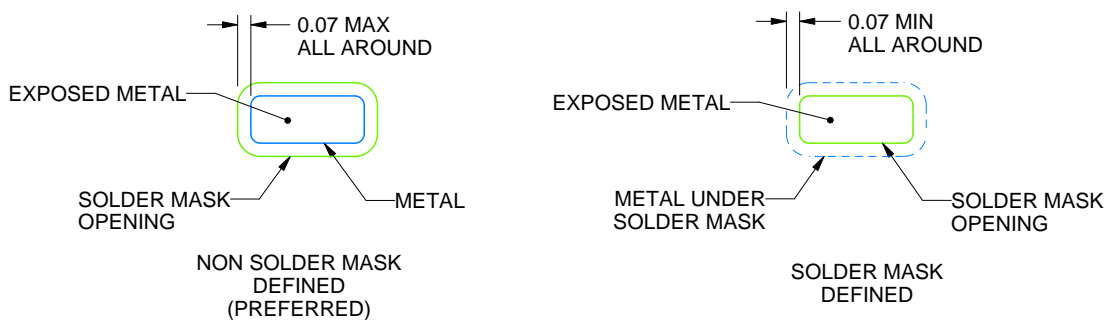
NGQ0008A

WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:20X



SOLDER MASK DETAILS

4214922/A 03/2018

NOTES: (continued)

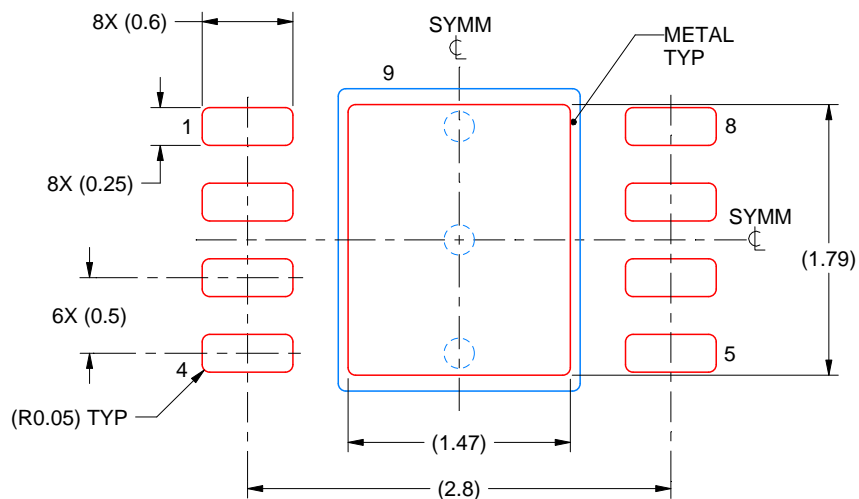
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slue271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

NGQ0008A

WSN - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD 9:
82% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

4214922/A 03/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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